## **APPLICATION DATA SHEET**

Electronic Version v14

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Title of Invention

[MOLD AND METHOD OF MOLDING SEMICONDUCTOR DEVICES]

Application Type : regular, utility
Attorney Docket Number : 11184-US-PA

Correspondence address:

Customer Number: 31561

**Priority Data:** 

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.